

MacDermid Alpha Releases CircuEtch 200 Anisotropic Final Etch for SAP and mSAP

(Waterbury, CT USA) – November 2nd, 2020 – MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of CircuEtch 200, a high performance anisotropic final etch for circuit formation in Semi-Additive and modified-Semi-Additive processes (SAP/mSAP) utilized in IC substrate and substrate-like HDI manufacturing.

As the demands for electronic devices grow increasingly complex with new mobile and infrastructure applications in the 5G rollout, both the circuit board and IC substrate continue to grow in component and circuit density. The CircuEtch 200 anisotropic final etch is the latest addition to the MacDermid Alpha process family for the manufacturing of the advanced HDI utilized in these new applications. In the additive build-up process utilized in mSAP and SAP, the final etch that is used to define the fine line features of the layer must be an extremely stable process with a wide operating window to allow for extremely low defect rates. CircuEtch 200 precisely defines traces with optimal geometry, zero undercut, and vertical trace sidewalls for excellent electrical performance. The bath has a predictable etching rate over a wide range of additive, copper, acid, chloride concentration and operating temperatures, while running in easy to maintain horizontal spray etching equipment. The high-speed etching of CircuEtch 200 can remove up to 5 microns of electrodeposited copper foil or electroless copper seed layer per minute while reducing the surface roughness of the pattern plated electrolytic copper traces for improved surface properties.

For more information on CircuEtch 200, please visit [MacDermidAlpha.com](https://www.MacDermidAlpha.com)

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